



Advacam Oy
Tietotie 3, 02150 Espoo
Finland

Assembly packaging list

Date: 2018-09-05
Person: Akiko Gädä

Purchase order number 60003436

Date:	Step:	Person:
2018-05-03	Hi-accuracy calibration:	AG
2018-09-05	Calibration:	AG
2018-09-05	Test bondings:	AG
2018-09-05	Flip chip bonding	AG

2018-09-05 TPIX3 - Si 3D modules for NIKHEF

#	Assembly (sensor) id #	Assembly (ROC) id #	ASIC wafer id #	ASIC type	ASIC id#	Sensor wafer / batch	Sensor chip	Thickness (um)	Bonding comments
1	5128-5 M1	W011-AEPVZ1H-I5	W011-AEPVZ1H	TPIX3	I5	5128	5 M1	?	OK-
2	5128-7 M7	W011-AEPVZ1H-D4	W011-AEPVZ1H	TPIX3	D4	5128	7 M7	?	OK-
3	5128-7 M6	W011-AEPVZ1H-E4	W011-AEPVZ1H	TPIX3	E4	5128	7 M6	?	OK
4	5128-10 M2	W011-AEPVZ1H-G3	W011-AEPVZ1H	TPIX3	G3	5128	10 M2	?	OK

